AMP

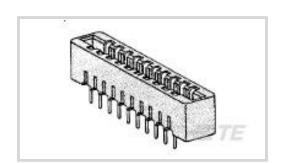
TE Internal #: 7-530671-2

TE Internal Description: CONN LOW PRO 10 POS 125X200C/L

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > Standard Edge Connectors



Connector System: Board-to-Board

Number of Positions: 10

Centerline (Pitch): 3.18 mm [.125 in]

Termination Method to Wire & Cable: Solder Eyelet

Number of Dual Positions: 10

Features

Product Type Features

Connector System	Board-to-Board
Connector & Housing Type	Receptacle
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	10
Number of Dual Positions	10
Number of Rows	2
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical

Body Features

Primary Product Color	Green	
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Contact Features

Contact Retention Within Housing	With
PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]
Contact Type	Socket
Contact Mating Area Plating Material Thickness	.76 μm
Contact Mating Area Plating Material	Gold
PCB Contact Termination Area Plating Material Finish	Bright
Contact Underplating Material	Nickel



PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Current Rating (Max)	5 A
Termination Features	
Termination Post & Tail Length	3.81 mm[.15 in]
Termination Method to PCB	Through Hole - Solder
Termination Method to Wire & Cable	Solder Eyelet
Mechanical Attachment	
Mating Retention	Without
Mating Alignment	Without
Contact Retention Type Within Housing	Locking Lance
PCB Mount Alignment	Without
PCB Mount Retention	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	3.18 mm[.125 in]
Housing Material	Glass-Filled Polyester
Dimensions	
Card Slot Depth	7.49 mm[.29 in]
Connector Height	11.68 mm[.46 in]
Row-to-Row Spacing	5.08 mm[.2 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Power
Packaging Features	
Packaging Quantity	240
Packaging Method	Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought





















Documents

Product Specifications
Product Specification

English